

**PATTERN FORMATION METHOD AND PATTERN FORMATION
APPARATUS, EXPOSURE METHOD AND EXPOSURE APPARATUS,
AND DEVICE MANUFACTURING METHOD**

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ABSTRACT

In a measurement zone that is spaced apart in a Y-axis direction from an exposure zone that is located immediately below a projection unit (PU), a detection area of an alignment system (ALG) is moved in the Y-axis direction and a plurality of marks are sequentially detected, and therefore a movement distance of wafer stages (WST1, WST2) in the Y-axis direction when performing the mark detection can be decreased compared with the case where only the wafer stages are moved while fixing the alignment system and mark detection is performed as in the conventional cases. Accordingly, a width of the measurement zone in the Y-axis direction can be reduced, which allows the apparatus to be downsized.

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Fig. 10